12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260330004.2
Qualification of Amkor Korea as an Additional Bump site and Assembly site for Select Devices
Change Notification / Sample Request

Date: March 30, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260330004.2
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
AM62A34ASMSIAMBRQ1	NULL
AM62A74AUMSIAMBRQ1	NULL
AM62A32ASMSIAMBRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260330004.2	**PCN Date:**	March 30, 2026
Title:	Qualification of Amkor Korea as an Additional Bump site and Assembly site for Select Devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	September 26, 2026	**Sample requests accepted until:**	May 29, 2026*

*Sample requests received after May 29, 2026 will not be supported.

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of Amkor Korea as an additional Bump site and Assembly site for select devices. No Material differences between sites.

	Current site	Additional site
Bump site	SCK	AK5
Assembly site	SCK	AK4

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

AM62A12AQMSIAMBRQ1	AM62A34ASMSIAMBRQ1	AM62A34AMLSIAMBRQ1
AM62A32ASMSIAMBRQ1	AM62A74AUMSIAMBRQ1	

Qualification Report
Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)

AM62A AMB 2nd Source Amkor
Approve Date 12-January-2026

Product Attributes

Attributes	Qual Device: XAM62A74ATMGGIAMB	QBS Package Reference: XJ721EGALF
Automotive Grade Level	Custom Tj (Grade 2 Test Conditions)	Custom Tj (Grade 2 Test Conditions)
Operating Temp Range (C)	-40 to 125C Tj	-40 to 125C Tj
Product Function	Microprocessor	Microprocessor
Die Attributes		
Wafer Fab Supplier	TSMC-F14	TSMC-F14
Wafer Process	CLN16FFC	CLN16FFC
Package Attributes		
Assembly Site	ANA	ANA
Package Group	FCHIP	FCHIP
Package Designator	AMB	ALF
Package Size (mm)	18 x 18	24 x 24
Body Thickness (mm)	2.512	2.18
Pin Count	484	827
Lead Finish	SNAGCU	SNAGCU
Lead Pitch(mm)	0.8	0.8

QBS: Qual By Similarity, also known as Generic Data
Qual Device XAM62A74ATMGGIAMB is qualified at MSL3 250C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: XAM62A74ATMGGIAMB	QBS Package Reference: XJ721EGALF
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	3/600/0	-
HAST	A2	JEDEC JESD22-A110	3	77	Temperature Humidity Bias	85C/85%RH	1000 Hours	-	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	110C/85%RH	264 Hours	3/231/0	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-55C/125C	1000 Cycles	3/231/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	1/77/0
BLR	NA	JESD22-A104, Condition G, Soak Mode 4	1	32	BLR Temperature Cycle	-40C/125C	1000 Cycles		1/32/0
Test Group B - Accelerated Lifetime Simulation Tests									

HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	3/2400/0	
Test Group C - Package Assembly Integrity Tests									
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	3/30/0
SBS	C5	AEC Q100-009	3	10	Solder Ball Shear	5 balls from a minimum of 10 devices	-	-	3/30/0
BST	C7	JESD22-B117	3	5	Bump Shear Test	20 bumps/pillars from a minimum of 5 devices. Cpk > 1.67	-	1/5/0	-
Test Group D - Die Fabrication Reliability Tests									
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests									
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2404-084
[1]-8D report available upon request.
[2]-8D report available upon request.

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS

Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-18

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.